



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
* : Required Field			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	18-07-2018
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	MDG MD CHAMPION	Representative Title	MDG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance * true **Legal Declaration *** Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
M24C02-RMC6TG	CGZW*24021TA	A	P1C7	18-07-2018
	Amount	UoM	Unit type	ST ECOPACK Grade
	16.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	2X3X0.6	8	No lead	
Comment	Package : ZW UDFPN 2x3x0.6 8L 0.5MM PITCH 7558452			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	CGZW*24021TA				5000000.0	1000003.8
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	0.174	mg	supplier	die	Silicon (Si)	7440-21-3		0.165	mg	948276	10313
				supplier	metallization	Aluminium (Al)	7429-90-5		0.001	mg	5747	63
				supplier	Passivation	Silicon Nitride	12033-89-5		0.001	mg	5747	63
				supplier	Passivation	Silicon Oxide	7631-86-9		0.007	mg	40230	438
Lead-frame	M-011 Other inorganic materials	3.007	mg	supplier	alloy	Copper (Cu)	7440-50-8		2.918	mg	970228	182353
				supplier	alloy	Iron (Fe)	7439-89-6		0.070	mg	23357	4390
				supplier	alloy	Zinc (Zn)	7440-66-6		0.004	mg	1195	225
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.003	mg	836	157
				supplier	coating	Nickel (Ni)	7440-02-0		0.012	mg	4019	755
				supplier	coating	Palladium (Pd)	7440-05-3		0.001	mg	257	48
				supplier	coating	Gold (Au)	7440-57-5		0.000	mg	107	20
Die Attach	M-011 Other inorganic materials	0.335	mg	supplier	glue or soft solder	Silver (Ag)	7440-22-4		0.229	mg	684000	14341
				supplier	glue or soft solder	methylene diacrylate	42594-17-2		0.084	mg	250000	5242
				supplier	glue or soft solder	Dicyclopentenyloxyethyl methacrylate	68586-19-6		0.010	mg	30000	629
				supplier	glue or soft solder	Polymer of Polybutadiene + Anhydride	Proprietary		0.010	mg	30000	629
				supplier	glue or soft solder	Palladium (Pd)	7440-05-3		0.000	mg	1000	21
Wires	M-011 Other inorganic materials	0.011	mg	supplier	glue or soft solder	Bis(α,α-dimethylbenzyl) peroxide	80-43-3		0.002	mg	5000	105
				supplier	Bonding wire	Copper (Cu)	7440-50-8		0.011	mg	1000000	664
Encapsulation	M-011 Other inorganic materials	12.473	mg	supplier	Moulding Compound	silica vitreous	60676-86-0		10.967	mg	879308	685463
				supplier	Moulding Compound	Phenolic resin	Proprietary		0.572	mg	45883	35768
				supplier	Moulding Compound	Biphenyl epoxy resin	85954-11-6		0.896	mg	71817	55985
				supplier	Moulding Compound	carbon black	1333-86-4		0.025	mg	1995	1555
				supplier	Moulding Compound	Zinc hydroxide	20427-58-1		0.012	mg	997	778